

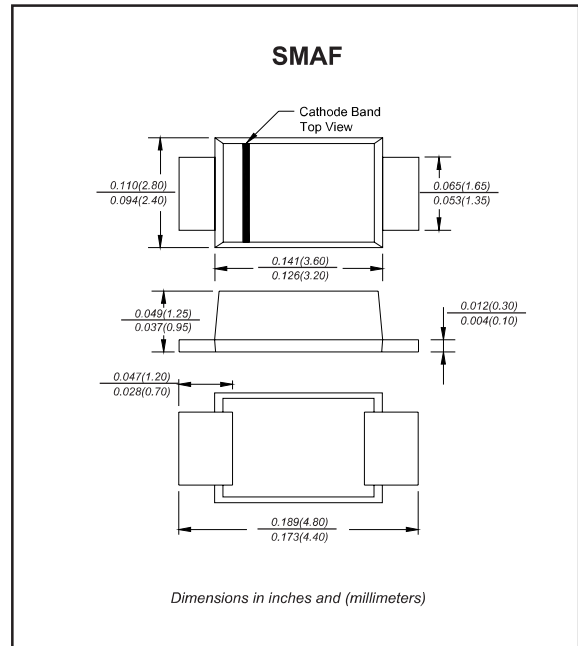
Features

- ▶ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ▶ For surface mounted applications
- ▶ Low reverse leakage
- ▶ Built-in strain relief, ideal for automated placement
- ▶ High forward surge current capability
- ▶ High temperature soldering guaranteed: 250°C/10 seconds at terminals
- ▶ Glass passivated chip junction
- ▶ Compliant to RoHS Directive 2011/65/EU
- ▶ Compliant to Halogen-free
- ▶ Suffix "-Q1" for AEC-Q101

Mechanical data

- ▶ **Case:** JEDEC SMAF molded plastic body
- ▶ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ▶ **Polarity:** Color band denotes cathode end
- ▶ **Mounting Position:** Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_O			3.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			80	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	I_R			5.0	μA
	$V_R = V_{RRM} \quad T_A = 125^\circ\text{C}$				500	
Thermal resistance	Junction to ambient NOTE 1	$R_{\theta JA}$		70		$^\circ\text{C}/\text{W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		38		pF
Storage temperature		T_{STG}	-55		+150	$^\circ\text{C}$

Note: 1.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature T_J , ($^\circ\text{C}$)
S3A-F-Q1	50	35	50	1.10	-55 to +150
S3B-F-Q1	100	70	100		
S3D-F-Q1	200	140	200		
S3G-F-Q1	400	280	400		
S3J-F-Q1	600	420	600		
S3K-F-Q1	800	560	800		
S3M-F-Q1	1000	700	1000		

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage@ $I_F=3.0\text{A}$

Rating and characteristic curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

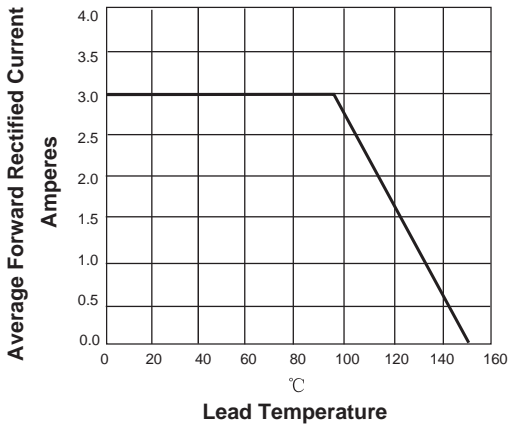


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

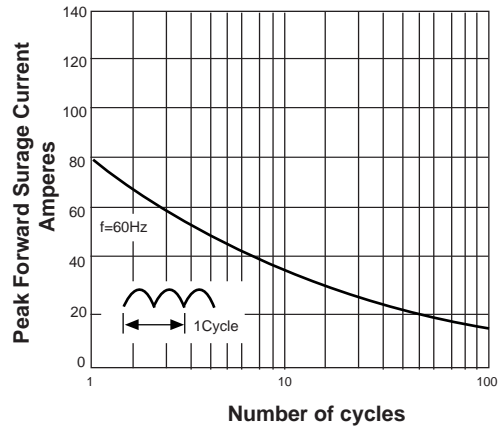


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

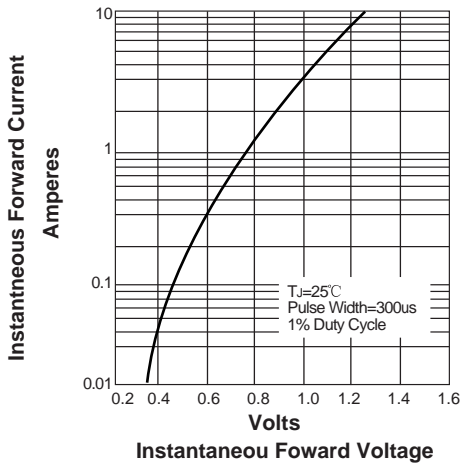
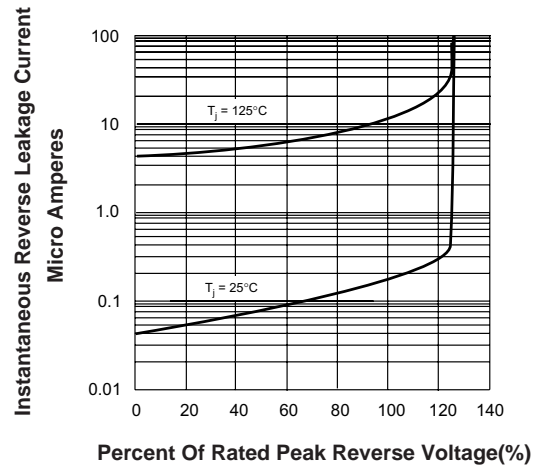
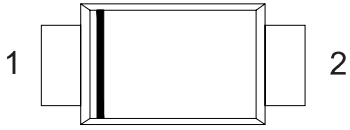



FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



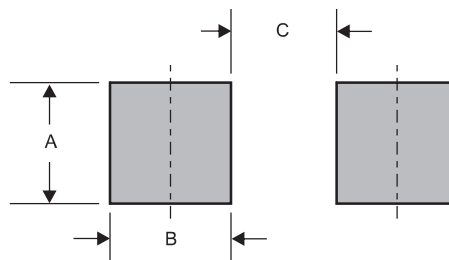
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
S3A-F-Q1	S3A
S3B-F-Q1	S3B
S3D-F-Q1	S3D
S3G-F-Q1	S3G
S3J-F-Q1	S3J
S3K-F-Q1	S3K
S3M-F-Q1	S3M

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMAF	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)